



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

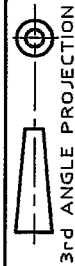
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



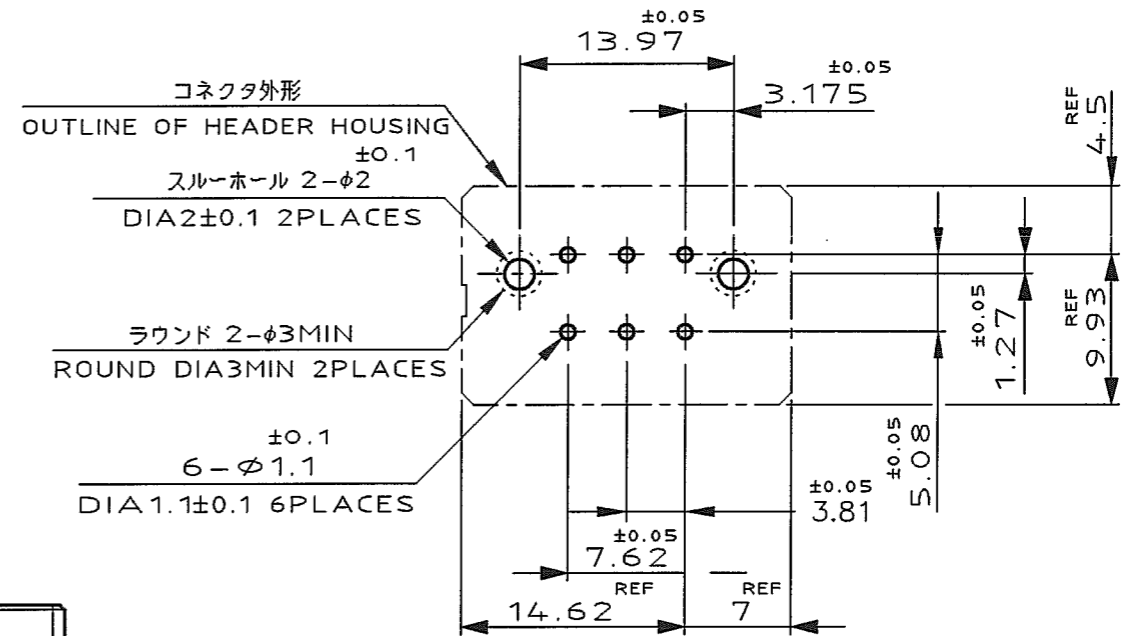
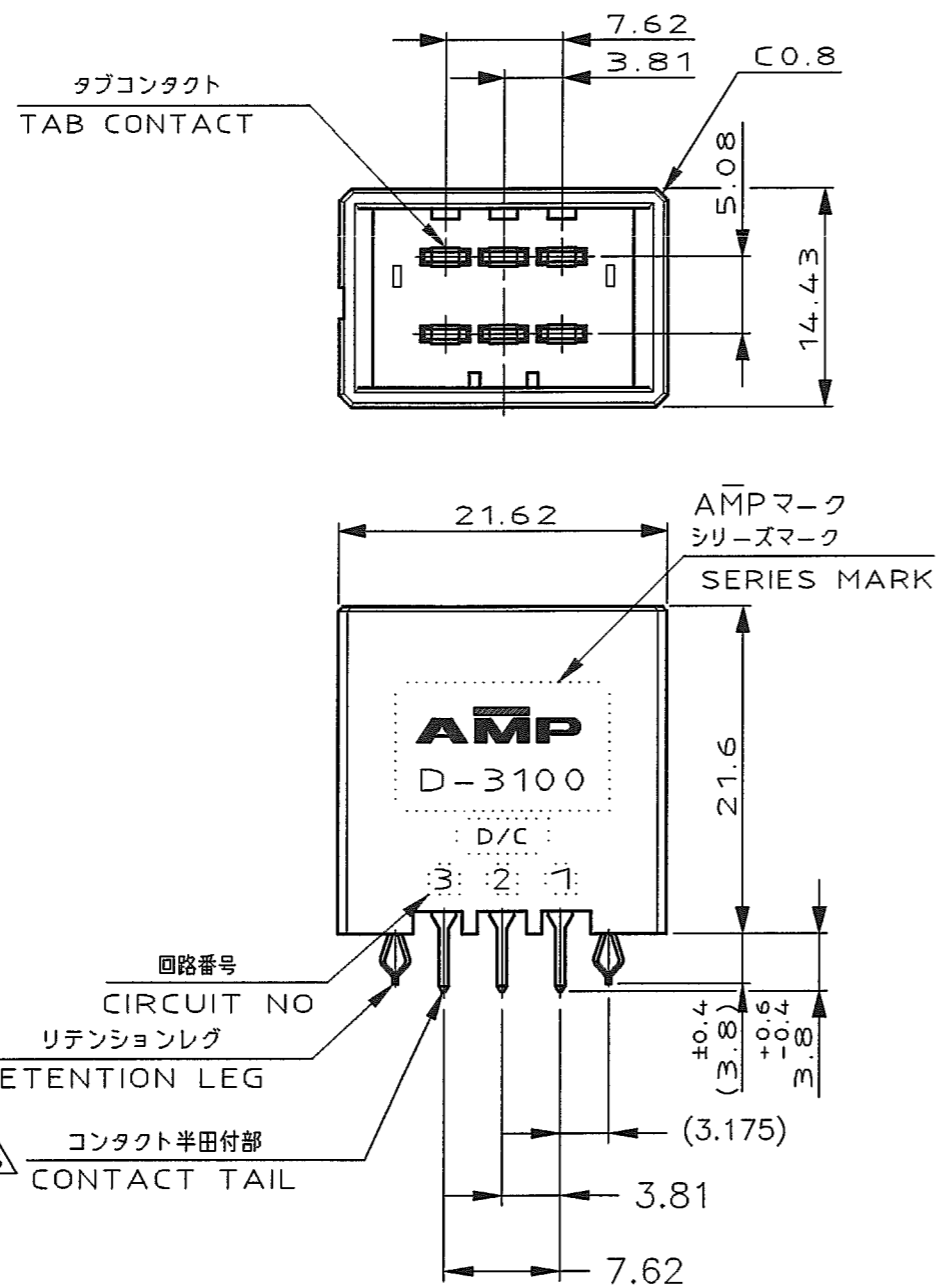
NUMBER 178323



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法

PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN-LEAD PLATED
(CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性
ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
3. めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
4. めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
5. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
6. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

△6	△4	178323-5
△6	△3	178323-3
△6	△2	178323-2
(FINISH)		製品番号 (PART NO.)

D1	REVISED PER ECO-11-005030	RK	HMR	23MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA	NAME	
mm (AWG -)		mmφ	DOUBLE ROW (D-3100)	
MATERIAL		FINISH	DYNAMIC CONN. 6POS. VERTICAL HDR. ASS'Y	
SEE NOTE		SEE NOTE		
注記参照		注記参照		
DR. 15 FEB 91		DE. 15 FEB 91	一般公差 (GENERAL TOLERANCE)	
N. Matsubara		N. Matsubara	10%以下: ±0.3	
CHK. 21 MAY '91		APP. 21-MAY-'91	10%以下 30%以下: ±0.4	
T. Obata		S. MANABE	30%以下 100%以下: ±0.5	
			角 度: ±3'	
			SIZE	LOC
			A3	J
			NUMBER	
			C-178323	
			SCALE	REV.
			2-1	D1
			SHEET	
			1 OF 1	

